Features

- Virgin polypropylene or Kynar[®] PVDF comes in contact with the process fluid
- Thick plastic jacketing is welded in place
- No cracks, joints, or crevices to collect contaminants
- Suitable for fluids used in silicon chip and electronics manufacturing
- For extremely corrosive industrial processes such as hydrofluoric acid plants, pickling lines, and plating solutions
- Plastic surfaces are flame smoothed for the best available surface

Description -

The Delta Controls **Model P66** Capacitance Probe uses all plastic wetted parts and is intended for sanitary service. The probe is designed for **use in processes** and **storage tanks** where the possibility of contamination is prohibited. Process examples include injectable solutions, pharmaceutical dilution fluids, heavy water for research, electronic chipmaking, and high quality plating systems.

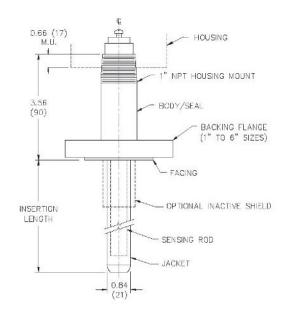
The P66 is also commonly used in industrial process systems which are extremely corrosive. **Kynar® PVDF is highly inert** and unaffected by almost all strong acids and bases below a temperature of +275 °F (+135 °C). Applications include hydrofluoric acid level, refinery hydroformers, bromine condensers, chlorine generation cells, radioactive processes, and wastes.

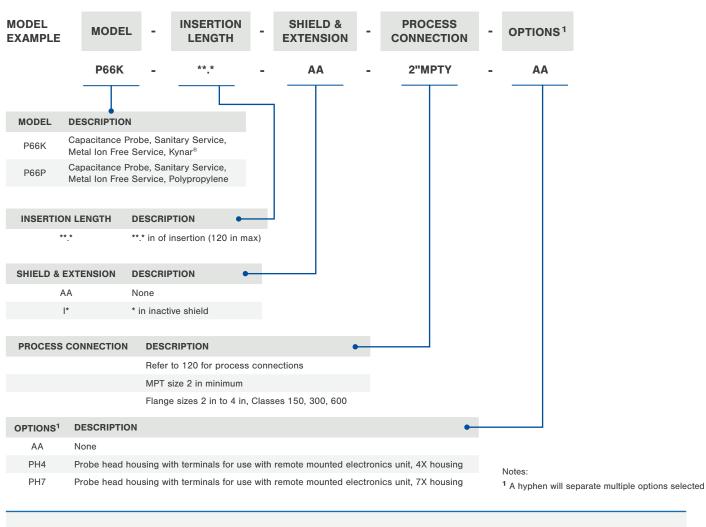


Model P66

Specifications

Working Pressure:	-15 psig to +300 psig (-1.0 bar to +20.7 bar)
Working Temperature:	-40 °F to +300 °F (-40 °C to +149 °C)
Insertion Length:	≤ 10 ft (3 m)
Process Connection:	2.0 in minimum
Threaded Process Connection:	2.0 in to 3.0 in
Flanged Process Connection:	2.0 in to 4.0 in
Flange Rating:	≤ 600 lb
Available Wetted Materials:	Kynar® PVDF, Polypropylene, carbon steel (other materials available)





Model Numbering System

REQUIRED ORDERING INFORMATION:

- · Detailed model number
- Tag or nameplate detail (if required)
- Documentation & testing packages (if required, refer to Additional Resources)

APPLICATION DETAILS:

- Process fluid or material name*
- Process fluid or material dieletric constant
- Maximum process temperature
- Maximum process pressure

*Upper and lower materials required for interface service